

**AMENDMENTS TO THE CLAIMS**

1. (Original) A leadframe packaging apparatus comprising:  
a die;  
at least two separated die pads each connected to a  
corresponding voltage level thereof;  
a plurality of leadfingers; and  
at least one passive component having two ends each connected  
to one of said two separated die pads.

2. (Original) The leadframe packaging apparatus of claim 1  
wherein said voltage level is a power source voltage level and a  
ground voltage level.

3. (Original) The leadframe packaging apparatus of claim 2  
wherein said power source voltage level and said ground voltage  
level is supplied by a printed circuit board, which is further  
fixedly connected with said leadframe packaging apparatus.

4. (Currently Amended) The leadframe packaging apparatus of  
claim 1 further comprising a busbar disposed between two non-  
adjacent leadfingers and extended from at least one of the non-  
adjacent leadfingers.

5-7. (Cancelled)

8. (Currently Amended) A packaging method for a leadframe packaging apparatus comprising steps as follows:

preparing an integrated circuit die;

adhering said integrated circuit die into ~~a die pad~~ at least two separated die pads, each connected to a corresponding voltage level;

preparing at least one passive component having two ends, each connected to one of said two separated die pads respectively;

wirebonding said integrated circuit die;

preparing a molding compound for placing said integrated circuit die, said die pad, and said passive component therein;

defining said leadfingers outside of said molding compound as first leadfinger sections and said leadfingers inside of said molding compound as second leadfinger sections; and ^

electrically connecting said first leadfinger sections with a printed circuit board and said second leadfinger sections with said integrated circuit ~~board~~ die.

9. (Currently Amended) The packaging method of claim 8 further comprising a step of having a busbar ~~bridged~~ disposed between two non-adjacent said second leadfinger sections.

10. (Currently Amended) The packaging method of claim 9, ~~wherein said passive component further bridges~~ further comprising a step of preparing at least one passive component bridging one of two non-adjacent said second leadfinger sections and said busbar.

11. (Currently Amended) The packaging method of claim 8 ~~wherein the passive component is further bridged between~~ further comprising a step of preparing at least one passive component bridging two adjacent said second leadfinger sections.

12. (Original) The packaging method of claim 8 further comprising a step of metalizing a bottom surface of said integrated circuit die before adhering said integrated circuit die into said die pad.

13. (Original) The packaging method of claim 8 wherein wirebonding said integrated circuit die is to wirebond a plurality of metal wires to said second leadfinger sections.

14. (Original) The packaging method of claim 8 wherein said leadfingers is made of an alloy.

15. (Currently Amended) The packaging method of claim 8 ~~wherein said passive component further bridges~~ further comprising a step of preparing at least one passive component bridging two adjacent said first leadfinger sections.